



(2,00 mm) .0787"

HDAM, HDAF SERIES



HDAM-11-12.0-S-13-2



HDAF-11-08.0-S-13-2

RUGGED ELEVATED HIGH DENSITY ARRAY

HDAM Mates with:
HDAF

HDAF Mates with:
HDAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAM or www.samtec.com?HDAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Current Rating:

2.3A per contact

@ 80°C ambient

Operating Temp Range:

-55°C to +125°C

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Contact Resistance:

19 mΩ

Working Voltage:

200 VAC

Mated Cycles:

100

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

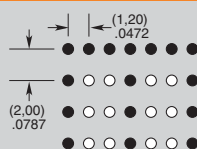


FILE NO. E111594



PATENT PENDING

DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

ALSO AVAILABLE

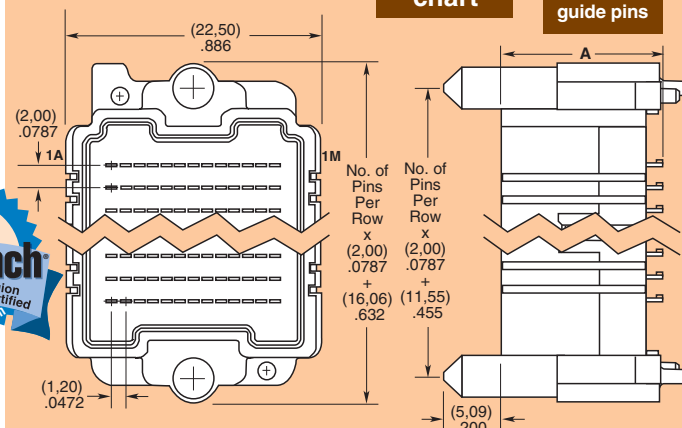
Tin-Lead Solder Charge.
Call Samtec.

Note: Other Gold plating options available. Contact Samtec.

Note: HD Mezz is a trademark of Molex Incorporated

Note: Some lengths, styles and options are non-standard, non-returnable.

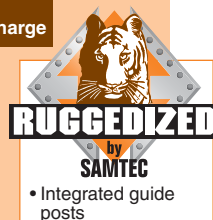
HDAM	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tails and guide pins	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge	-P = Pick & Place Pad



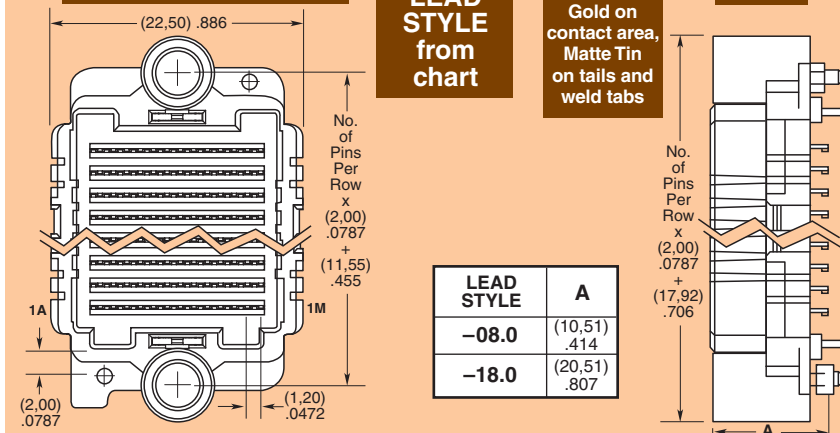
LEAD STYLE	A
-12.0	(14,41) .567
-17.0	(19,41) .764

HDAM/HDAF 35 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	9 GHz / 18 Gbps
Differential Pair Signaling	9 GHz / 18 Gbps

*Data based on simulations using Final Inch® design.
*Performance data includes effects of a non-optimized PCB.
Performance data for other stack heights and complete test data available at www.samtec.com?HDAM, www.samtec.com?HDAF or contact sig@samtec.com



HDAF	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tails and weld tabs	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/ 0.7% Cu Solder Charge	-P = Pick & Place Pad



LEAD STYLE	A
-08.0	(10,51) .414
-18.0	(20,51) .807



Due to technical progress, all designs, specifications and components are subject to change without notice.

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